

## N-channel 30 V, 0.018 $\Omega$ typ., 8 A, P-channel 30 V, 0.045 $\Omega$ typ., 5 A Power MOSFET in a SO-8 package

Datasheet - production data

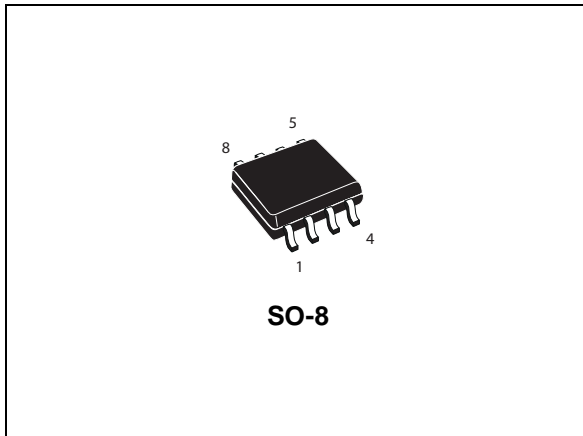
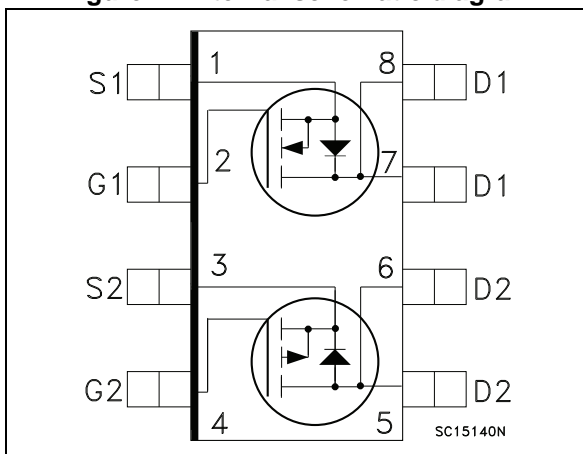


Figure 1. Internal schematic diagram



### Features

Order code	Channel	$V_{DS}$	$R_{DS(on)}$ max	$I_D$
STS8C5H30L	N	30 V	0.022 $\Omega$	8 A
	P		0.055 $\Omega$	5 A

- Conduction losses reduced
- Switching losses reduced
- Low threshold drive
- Standard outline for easy automated surface mount assembly

### Applications

- Switching applications

### Description

This device is a complementary N-channel and P-channel Power MOSFET developed using STripFET™ II (P-channel) and STripFET™ V (N-channel) technologies. The resulting transistors show extremely high packing density for low on-resistance and rugged avalanche characteristics.

Table 1. Device summary

Order code	Marking	Packages	Packaging
STS8C5H30L	8C5H30L	SO-8	Tape and reel

# Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		N-channel	P-channel	
$V_{DS}$	Drain-source voltage	30		V
$V_{GS}$	Gate- source voltage	±16	±16	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$ single operating	8	5.4	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$ single operating	6.4	4.3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	32	21.6	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$ dual operating	1.6		W
	Total dissipation at $T_C = 25^\circ\text{C}$ single operating	2		W
$T_{stg}$	Storage temperature	-55 to 150		$^\circ\text{C}$
$T_j$	Operating junction temperature	150		$^\circ\text{C}$

1. Pulse width limited by safe operating area

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-a}^{(1)}$	Thermal resistance junction-ambient single operating	62.5	$^\circ\text{C}/\text{W}$
$R_{thj-a}^{(1)}$	Thermal resistance junction-ambient dual operating	78	$^\circ\text{C}/\text{W}$

1. When mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz. Cu.,  $t \leq 10$  sec

*Note:* For the p-channel MOSFET actual polarity of voltages and current has to be reversed

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Channel	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0, I_D = 250\ \mu A$	N	30			V
			P	30			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0, V_{DS} = 30\ V$	N			1	$\mu A$
		$V_{GS} = 0, V_{DS} = 30\ V, T_C = 125\text{ °C}$	P			10	$\mu A$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0, V_{GS} = \pm 16\ V$	N			$\pm 100$	nA
		$V_{DS} = 0, V_{GS} = \pm 16\ V$	P			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu A$	N	1	1.6	2.5	V
			P	1	1.6	2.5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\ V, I_D = 4\ A$	N		0.018	0.022	$\Omega$
		$V_{GS} = 10\ V, I_D = 2.5\ A$	P		0.045	0.055	$\Omega$
		$V_{GS} = 4.5\ V, I_D = 4\ A$	N		0.020	0.025	$\Omega$
		$V_{GS} = 4.5\ V, I_D = 2.5\ A$	P		0.070	0.075	$\Omega$

Table 5. Dynamic

Symbol	Parameter	Test conditions	Channel	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 15\text{ V}, I_D = 4\text{ A}$	N	-	8.5		S
		$V_{DS} = 15\text{ V}, I_D = 2.5\text{ A}$	P	-	10		S
$C_{iss}$	Input capacitance	$V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N	-	857		pF
			P	-	1350		pF
$C_{oss}$	Output capacitance		N	-	147		pF
			P	-	490		pF
$C_{rss}$	Reverse transfer capacitance		N	-	20		pF
			P	-	130		pF
$Q_g$	Total gate charge	N-channel $V_{DD} = 24\text{ V}, I_D = 8\text{ A}$ $V_{GS} = 5\text{ V}$ P-channel $V_{DD} = 24\text{ V}, I_D = 4\text{ A}$ $V_{GS} = 5\text{ V}$ <i>(see Figure 27)</i>	N	-	7	10	nC
			P	-	12.5	16	nC
$Q_{gs}$	Gate-source charge		N	-	2.5		nC
			P	-	5		nC
$Q_{gd}$	Gate-drain charge		N	-	2.3		nC
			P	-	3		nC

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5.

For the p-channel MOSFET actual polarity of voltages and current has to be reversed

Table 6. Switching times

Symbol	Parameter	Test conditions	Channel	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	N-channel $V_{DD} = 15\text{ V}, I_D = 4\text{ A}$ $R_G = 4.7\ \Omega, V_{GS} = 4.5\text{ V}$ P-channel $V_{DD} = 15\text{ V}, I_D = 2\text{ A}$ $R_G = 4.7\ \Omega, V_{GS} = 4.5\text{ V}$ <i>Figure 26</i>	N	-	12	-	ns
			P	-	25	-	ns
$t_r$	Rise time		N	-	14.5	-	ns
			P	-	35	-	ns
$t_{d(off)}$	Turn-off delay time		N	-	23	-	ns
			P	-	125	-	ns
$t_f$	Fall time	N	-	8	-	ns	
		P	-	35	-	ns	

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Channel	Min.	Typ.	Max.	Unit
I <sub>SD</sub>	Source-drain current		N	-		8	A
			P	-		5	A
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		N	-		32	A
			P	-		20	A
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 8 A, V <sub>GS</sub> = 0	N	-		1.5	V
		I <sub>SD</sub> = 5 A, V <sub>GS</sub> = 0	P	-		1.2	V
t <sub>rr</sub>	Reverse recovery time	N-channel I <sub>SD</sub> = 8 A, di/dt = 100 A/μs V <sub>DD</sub> =15 V, T <sub>j</sub> =150 °C P-channel I <sub>SD</sub> = 5 A, di/dt = 100 A/μs	N	-	15		ns
			P	-	45		ns
Q <sub>rr</sub>	Reverse recovery charge		N	-	5.7		nC
			P	-	36		nC
I <sub>RRM</sub>	Reverse recovery current	V <sub>DD</sub> =15 V, T <sub>j</sub> =150 °C <i>Figure 28</i>	N	-	0.76		A
			P	-	1.6		A

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs, duty cycle 1.5%

Note: For the p-channel MOSFET actual polarity of voltages and current has to be reversed

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area n-ch

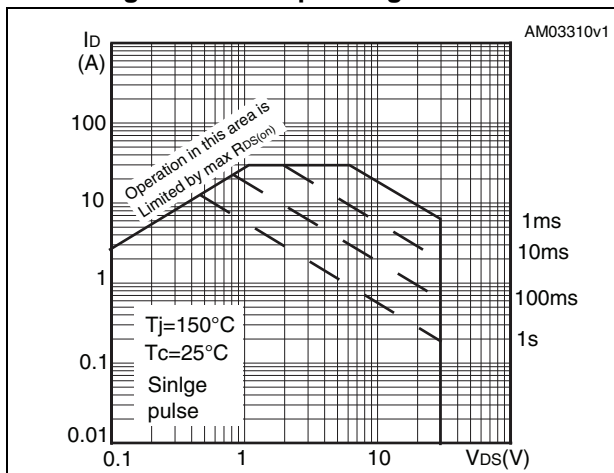


Figure 3. Thermal impedance n-ch

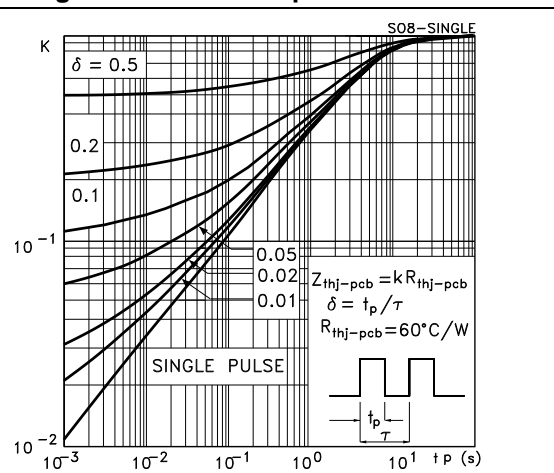


Figure 4. Output characteristics n-ch

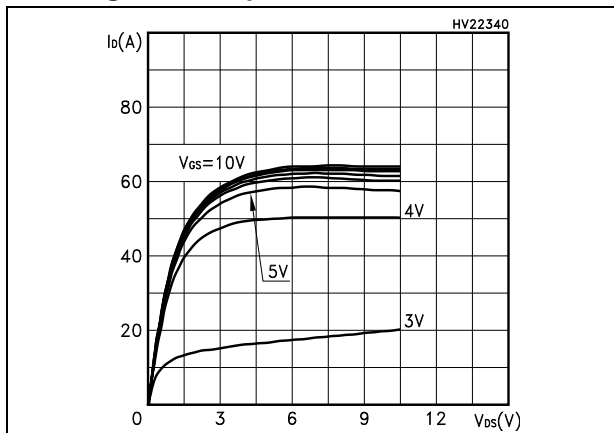


Figure 5. Transfer characteristics n-ch

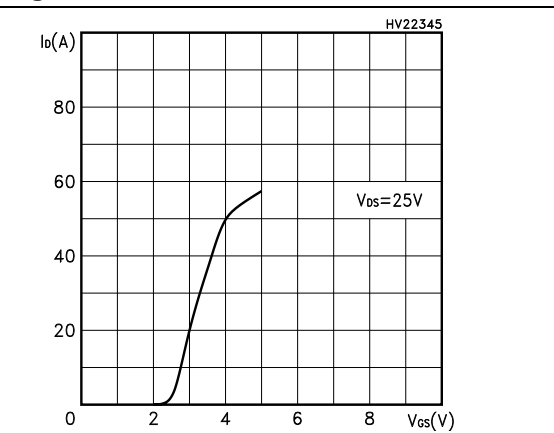


Figure 6. Transconductance n-ch

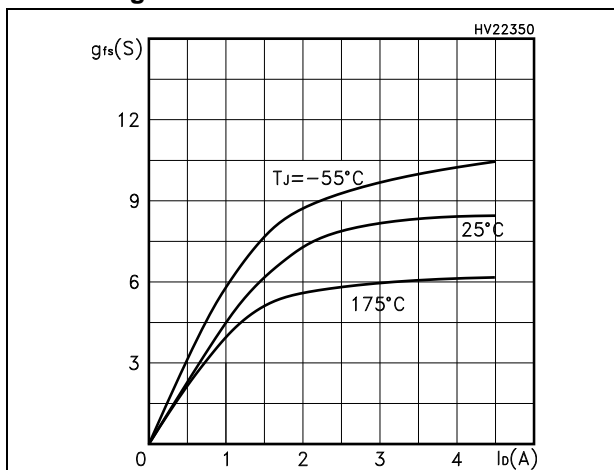


Figure 7. Static drain-source on resistance n-ch

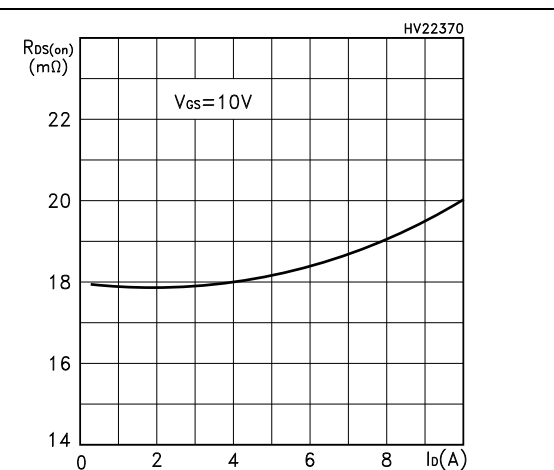


Figure 8. Gate charge vs. gate-source voltage n-ch

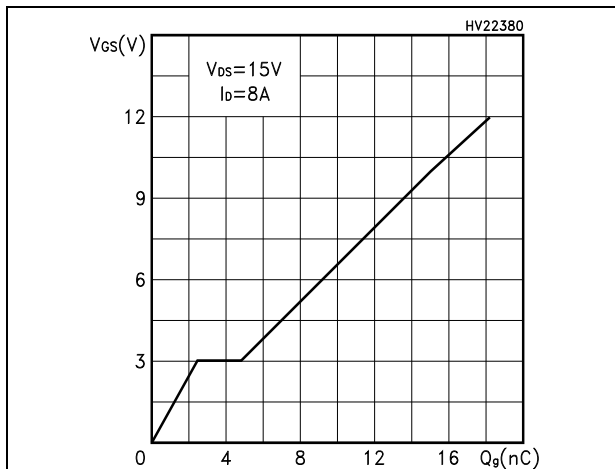


Figure 9. Capacitance variations n-ch

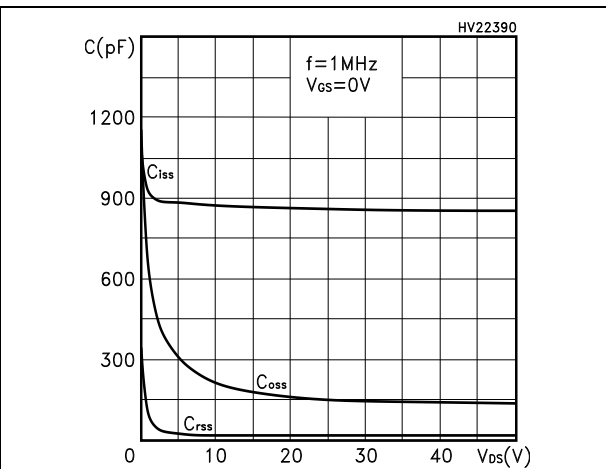


Figure 10. Normalized gate threshold voltage vs. temperature n-ch

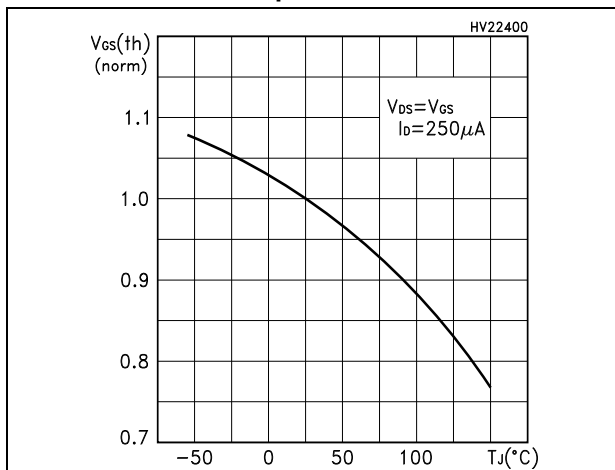


Figure 11. Normalized on resistance vs. temperature n-ch

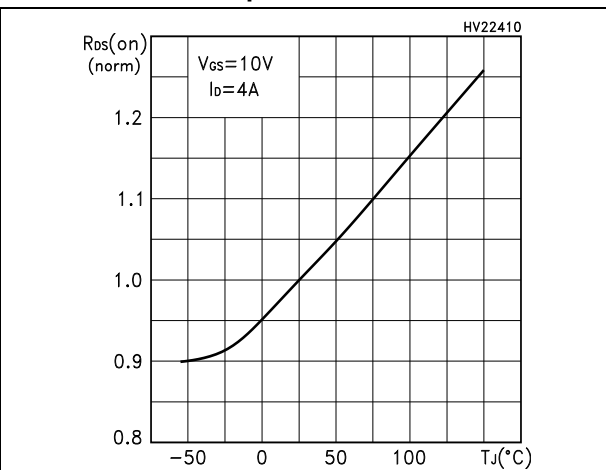


Figure 12. Source-drain diode forward characteristics n-ch

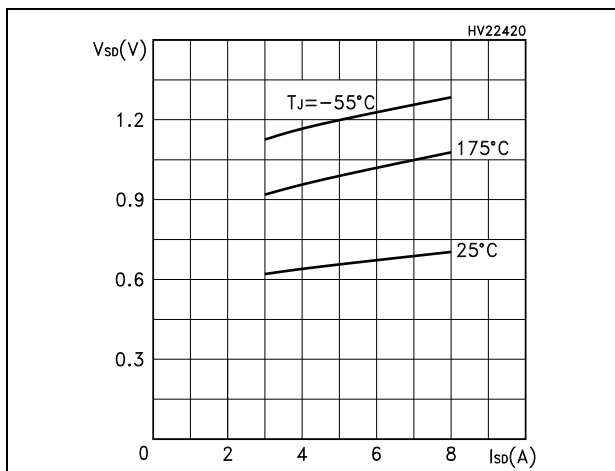


Figure 13. Normalized breakdown voltage vs. temperature n-ch

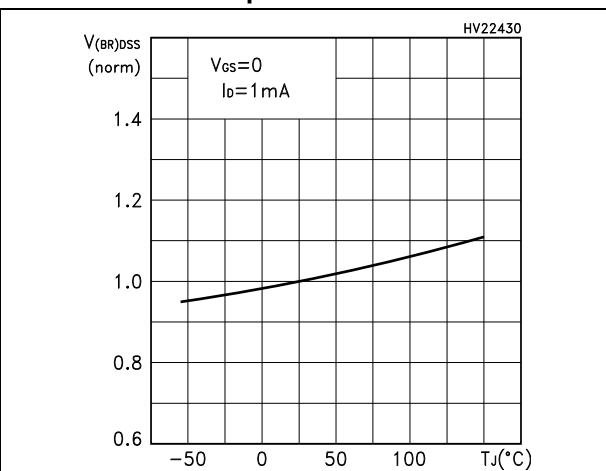




Figure 14. Safe operating area p-ch

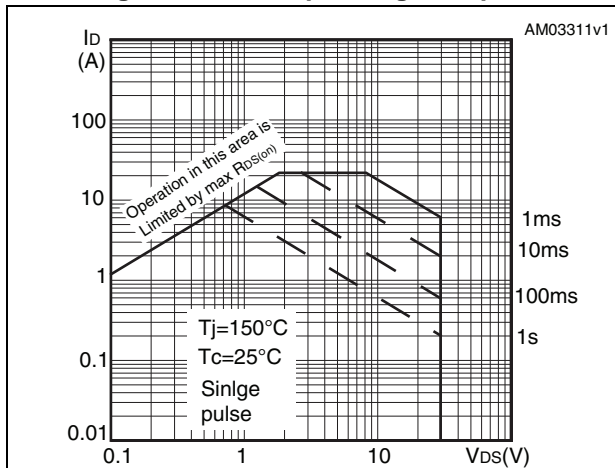


Figure 15. Thermal impedance p-ch

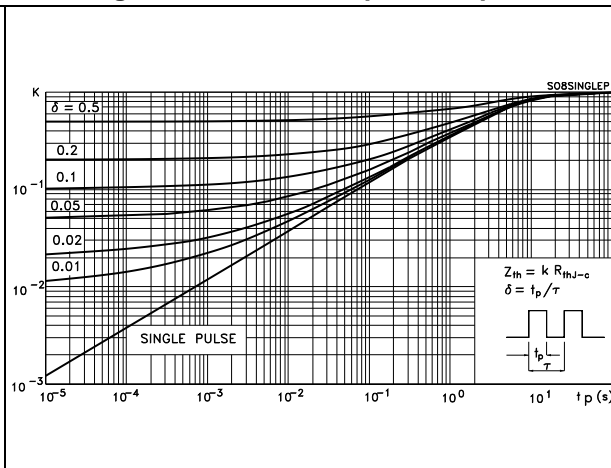


Figure 16. Output characteristics p-ch

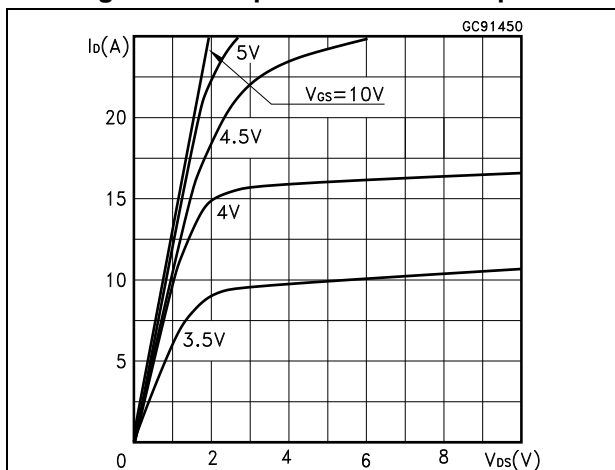


Figure 17. Transfer characteristics p-ch

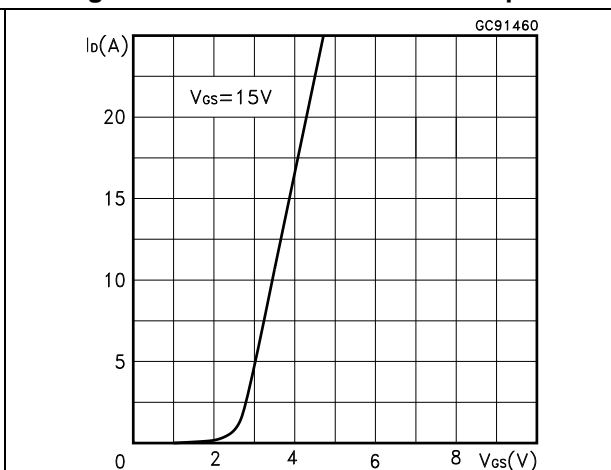


Figure 18. Transconductance p-ch

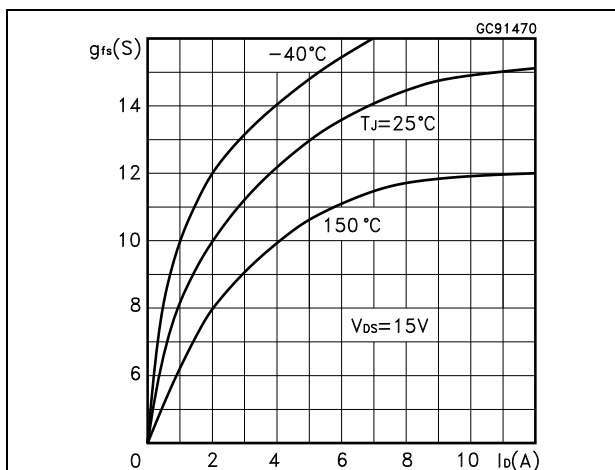


Figure 19. Static drain-source on resistance p-ch

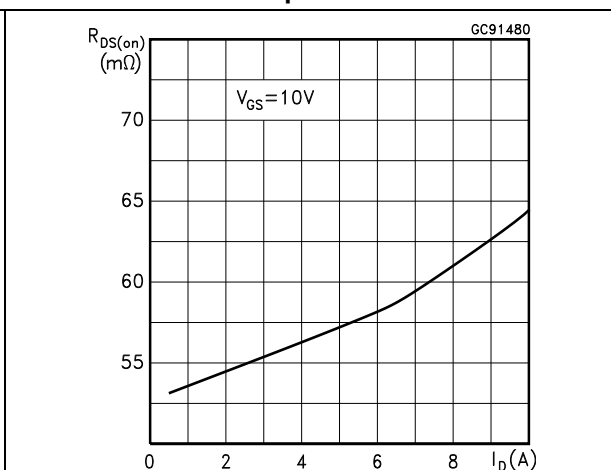


Figure 20. Gate charge vs. gate-source voltage p-ch

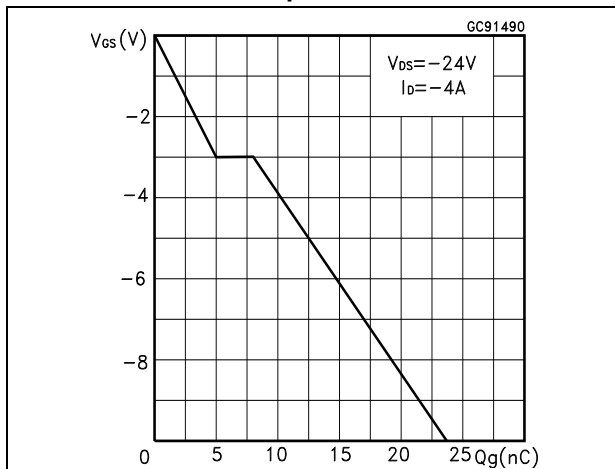


Figure 21. Capacitance variations p-ch

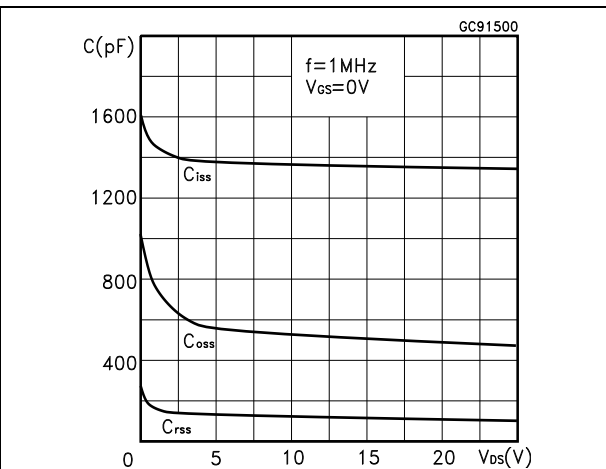


Figure 22. Normalized gate threshold voltage vs. temperature p-ch

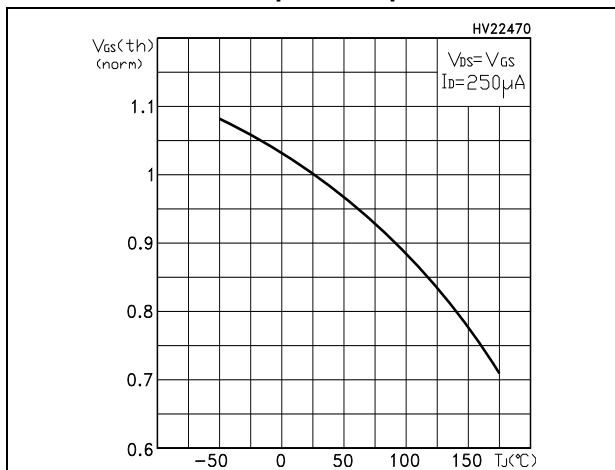


Figure 23. Normalized on resistance vs. temperature p-ch

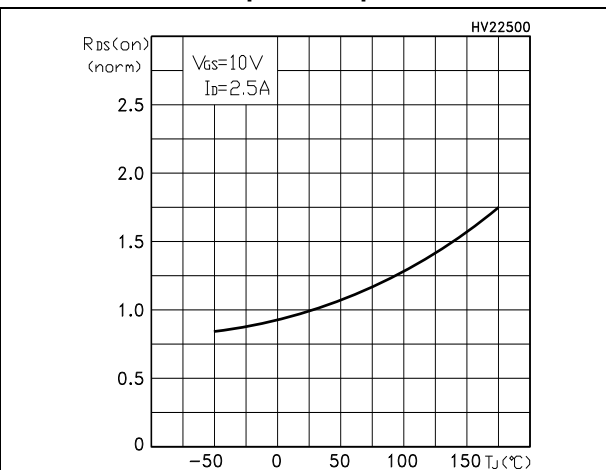


Figure 24. Source-drain diode forward characteristics p-ch

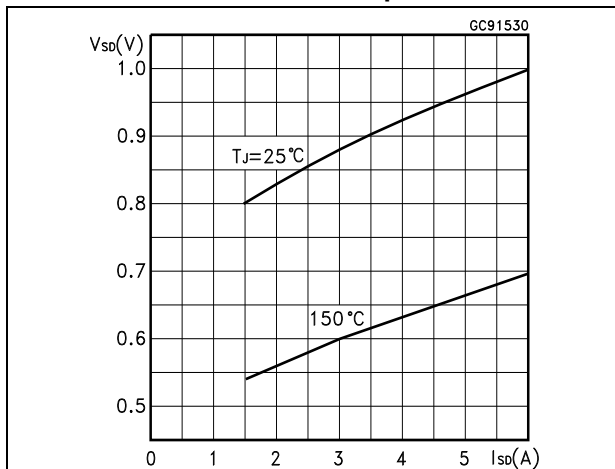
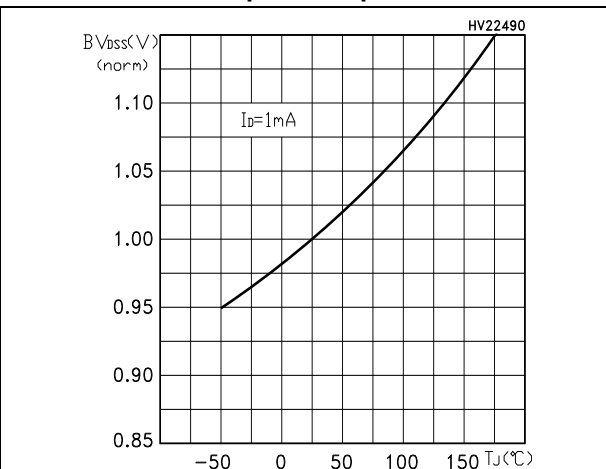
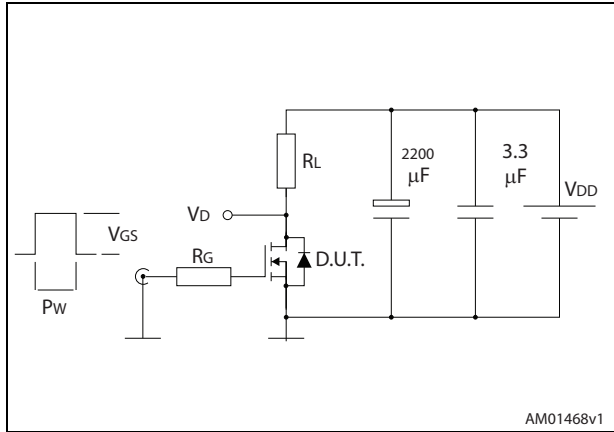


Figure 25. Normalized breakdown voltage vs. temperature p-ch



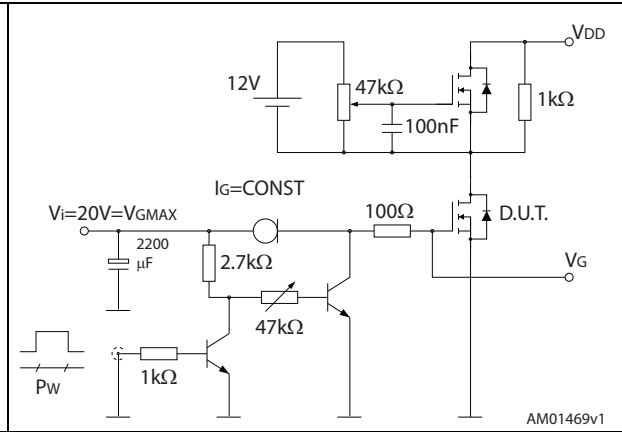
### 3 Test circuits

**Figure 26. Switching times test circuit for resistive load**



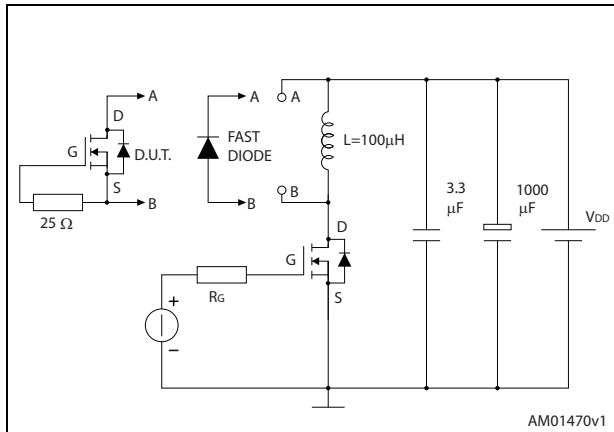
AM01468v1

**Figure 27. Gate charge test circuit**



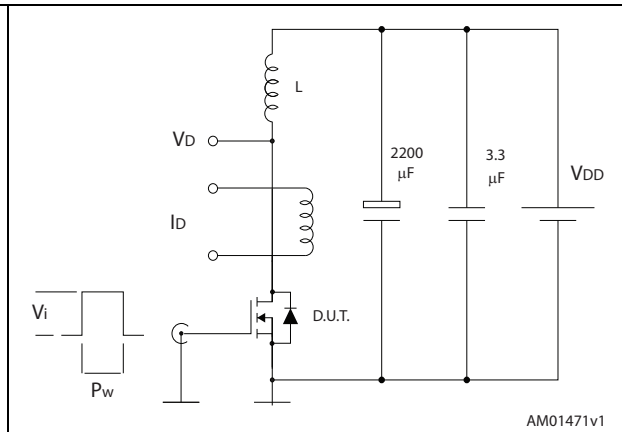
AM01469v1

**Figure 28. Test circuit for inductive load switching and diode recovery times**



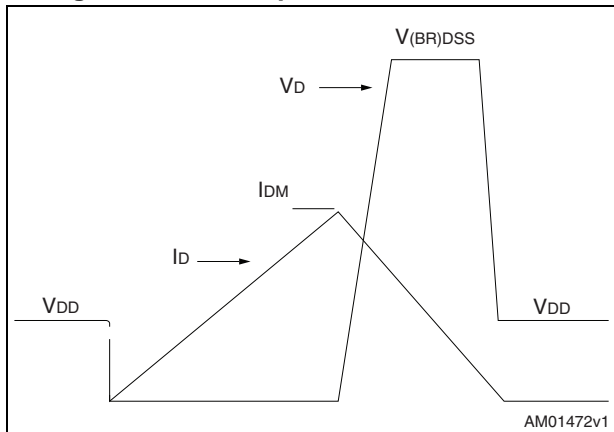
AM01470v1

**Figure 29. Unclamped inductive load test circuit**



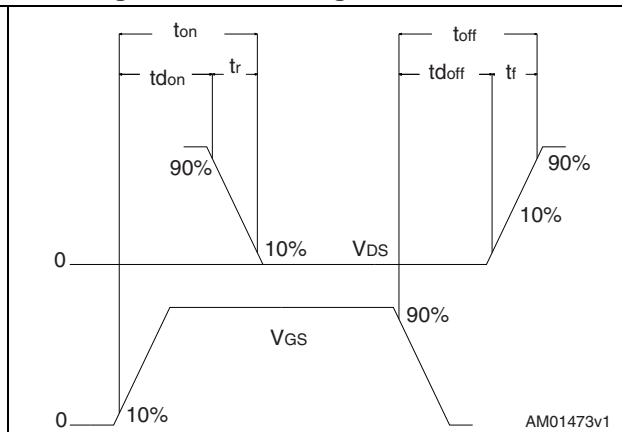
AM01471v1

**Figure 30. Unclamped inductive waveform**



AM01472v1

**Figure 31. Switching time waveform**



AM01473v1

## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

Figure 32. SO-8 drawing

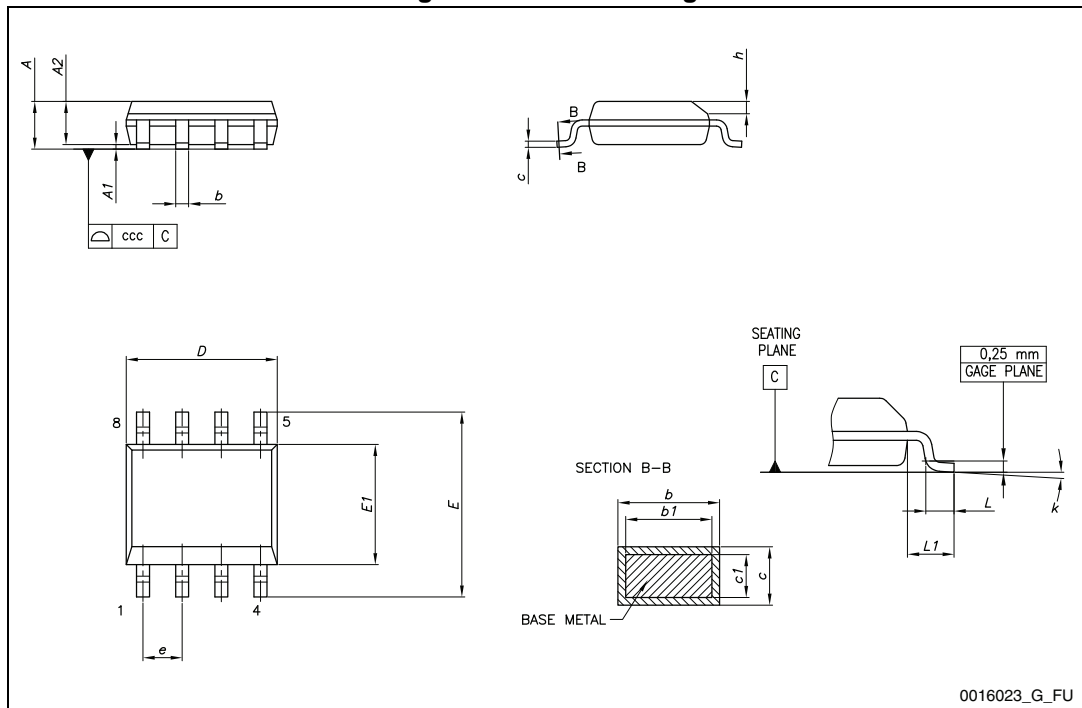
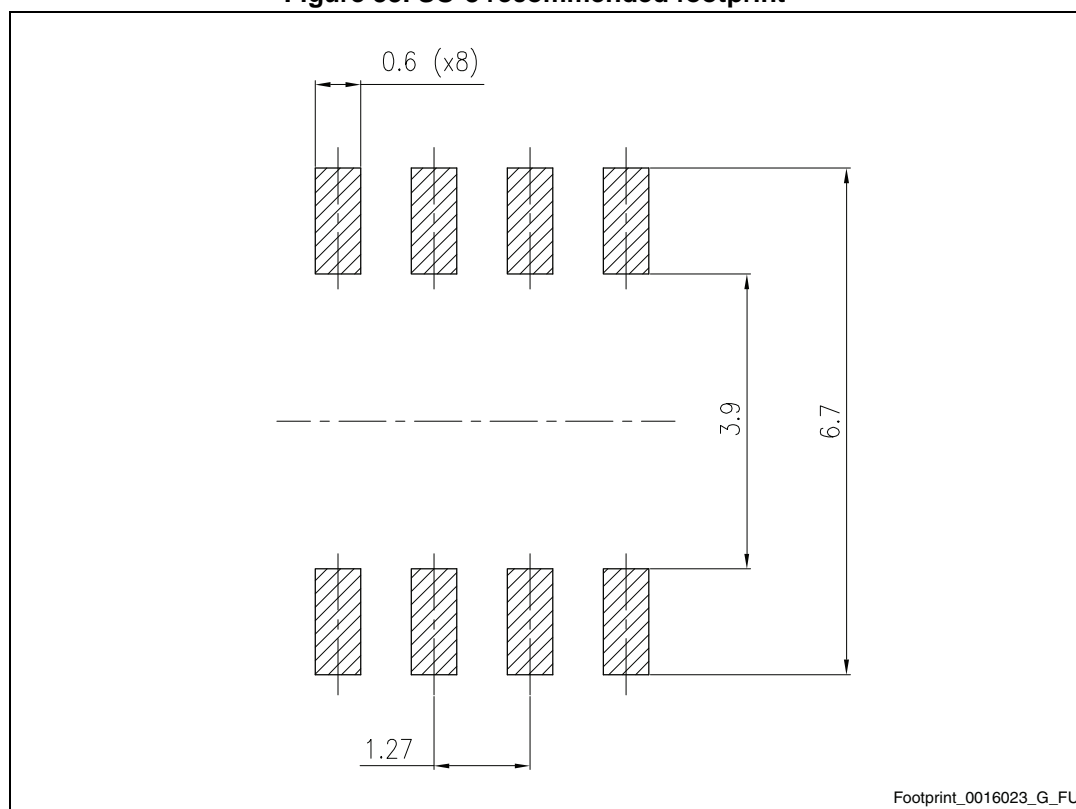


Table 8. SO-8 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
c	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

Figure 33. SO-8 recommended footprint<sup>(a)</sup>



a. All dimensions are in millimeters.

# 5 Packaging mechanical data

Figure 34. SO-8 tape and reel dimensions

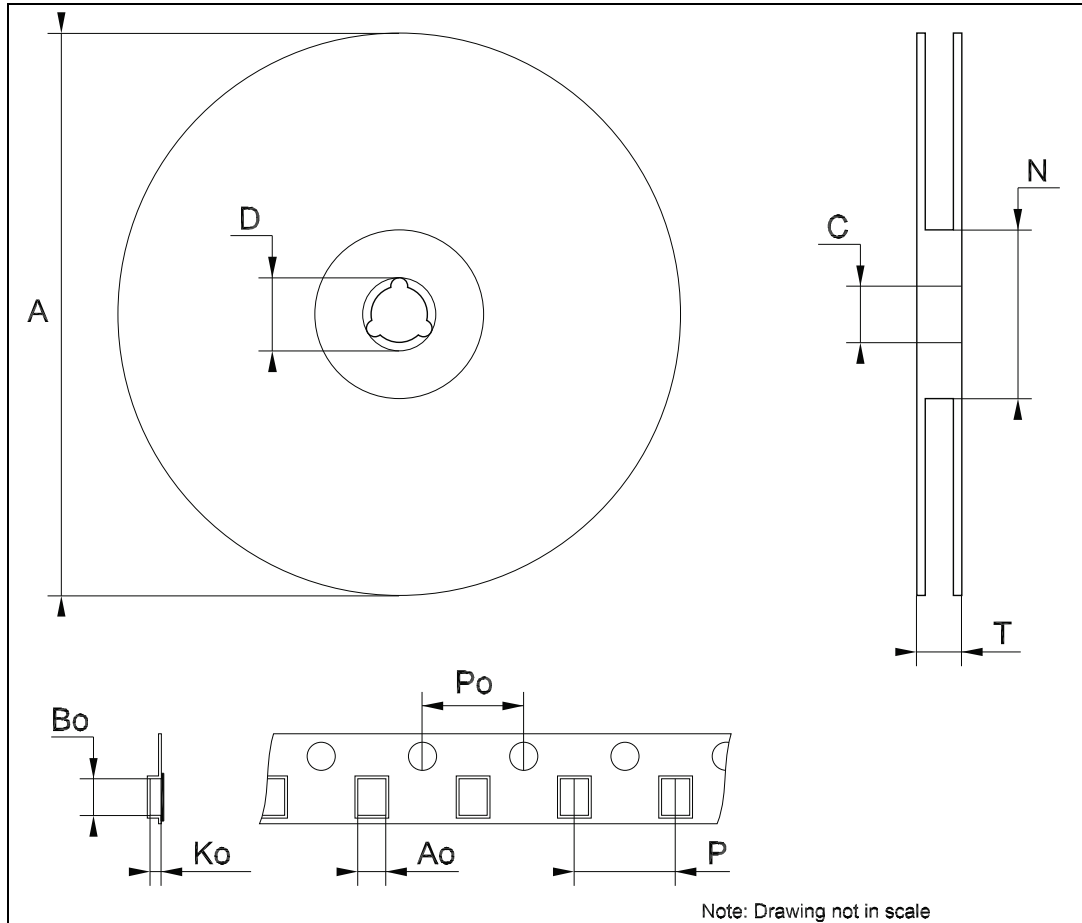


Table 9. SO-8 tape and reel mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A		-	330
C	12.8	-	13.2
D	20.2	-	
N	60	-	
T		-	22.4
Ao	8.1	-	8.5
Bo	5.5	-	5.9
Ko	2.1	-	2.3
Po	3.9	-	4.1
P	7.9	-	8.1



## 6 Revision history

Table 10. Revision history

Date	Revision	Changes
17-Sep-2004	1	First revision.
31-Oct-2006	2	The document has been reformatted.
30-Jan-2007	3	typo mistake on <a href="#">Table 2</a> .
23-Jul-2007	4	<a href="#">Figure 14</a> has been updated.
23-Feb-2009	5	<a href="#">Figure 2</a> , <a href="#">Figure 3</a> , <a href="#">Figure 14</a> and <a href="#">Figure 15</a> have been changed.
10-Jun-2010	6	Updated $V_{GS(th)}$ in <a href="#">Table 4: On/off states</a> .
13-Jun-2014	7	<ul style="list-style-type: none"> <li>– Modified: title</li> <li>– Modified: <a href="#">Description</a></li> <li>– Modified: marking in <a href="#">Table 1</a></li> <li>– Updated: <a href="#">Section 4: Package mechanical data</a></li> <li>– Minor text changes</li> </ul>

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[NTE6400](#) [SQJ402EP-T1-GE3](#) [2SK2614\(TE16L1,Q\)](#) [2N7002KW-FAI](#) [DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [ECH8691-TL-W](#)  
[FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE221](#) [NTE2384](#) [NTE2903](#) [NTE2941](#) [NTE2945](#) [NTE2946](#) [NTE2960](#) [NTE2967](#)  
[NTE2969](#) [NTE2976](#) [NTE455](#) [NTE6400A](#) [NTE2910](#) [NTE2916](#) [NTE2956](#) [NTE2911](#) [DMN2080UCB4-7](#) [TK10A80W,S4X\(S](#)  
[SSM6P69NU,LF](#) [DMP22D4UFO-7B](#) [DMN1006UCA6-7](#)